

Preliminary

## MOS Memories

MB81256

# FUJITSU

### ■ MB81256-10, MB81256-12, MB81256-15

NMOS 262,144-Bit Dynamic  
Random Access Memory

81256 LCC

#### Description

The Fujitsu MB81256 is a fully decoded, dynamic NMOS random access memory organized as 262,144 one-bit words. The design is optimized for high speed, high performance applications such as mainframe memory, buffer memory, peripheral storage and environments where low power dissipation and compact layout are required.

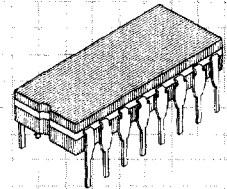
The MB81256 features "page mode" which allows high speed random access of up to 512-bits within the same row. Additionally, the MB81256 offers new functional enhancements that make it more versatile than previous dynamic RAMs. Multiplexed row and column address inputs permit the MB81256 to be housed in a Jedec standard 16-pin dual in-line package and 18-pad LCC.

The MB81256 is fabricated using silicon gate NMOS and Fujitsu's advanced Triple-layer Polysilicon process. This process, coupled with single transistor memory storage cells, permits maximum circuit density and minimal chip size. Dynamic circuitry is used in the design, including dynamic sense amplifiers.

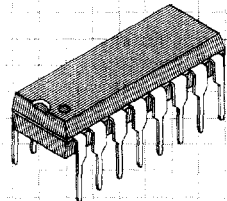
Clock timing requirements are noncritical, and the power supply tolerance is very wide. All inputs are TTL compatible.

#### Features

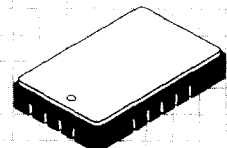
- 262,144 x 1-bit organization
- Row Access Time/Cycle Time:
  - MB81256-10  
100 ns Max/210 ns Min.
  - MB81256-12  
120 ns Max/230 ns Min.
  - MB81256-15  
150 ns Max/260 ns Min.
- Low Power Dissipation:
  - 314 mW max. ( $t_{AC} = 260$  ns)
  - 25 mW (Standby)
- +5V supply voltage,  $\pm 10\%$  tolerance
- All inputs TTL compatible, low capacitive load
- Three-state TTL compatible output
- Common I/O capability using "Early Write" operation
- On-chip substrate bias generator
- Page Mode Capability
- Fast Read-Write Cycle,  $TRWC = TRC$
- $t_{AR}$ ,  $t_{WCR}$ ,  $t_{DHR}$ ,  $t_{RWD}$  eliminated
- CAS-before-RAS on chip refresh
- Hidden CAS-before-RAS on-chip refresh
- RAS-only refresh
- 4 ms/256 cycle refresh
- Output unlatched at cycle end allows two dimensional chip select
- On-chip Address and Data-in latches
- Industry standard 16-pin package



Ceramic LCC  
DIP-16C-C04



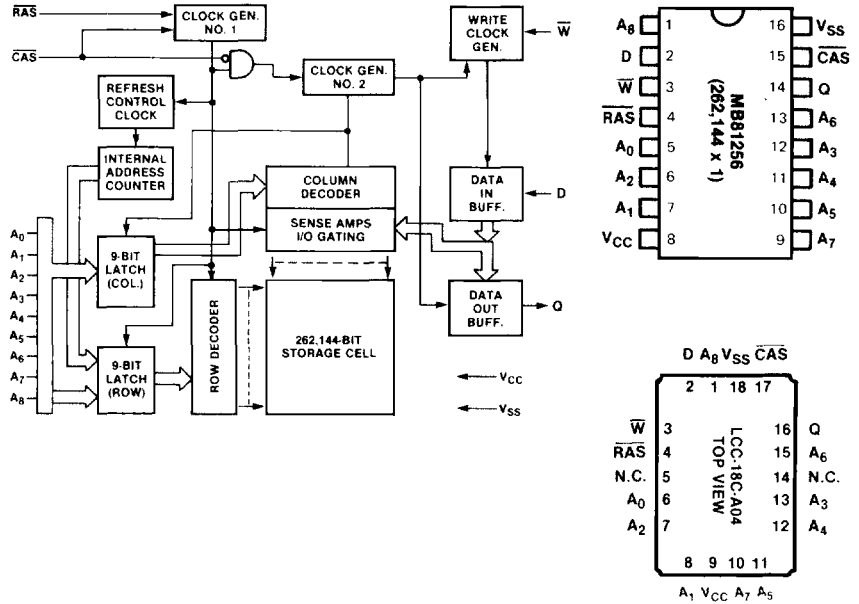
Plastic Package  
DIP-16P-M03



Ceramic LCC  
LCC-18C-F04

MB81256-10  
 MB81256-12  
 MB81256-15

**MB81256 Block Diagram and Pin Assignments**



81256LCC

NOTE: The following IEEE Std. 662-1980 symbols are used in this data sheet: D = Data In,  $\bar{W}$  = Write Enable, Q = Data Out.

**Absolute Maximum Ratings**  
 (See Note)

Rating	Symbol	Value	Unit
Voltage on Any Pin relative to V <sub>SS</sub>	V <sub>IN</sub> , V <sub>OUT</sub> , V <sub>CC</sub>	-1.0 to 7.0	V
Operating Temperature (ambient)	T <sub>OP</sub>	0 to 70	°C
Storage Temperature	Gerdip Plastic T <sub>STG</sub>	-55 to +150 -55 to +125	°C
Power Dissipation	P <sub>D</sub>	1.0	W
Short Circuit Output Current	I <sub>OS</sub>	50	mA

NOTE: Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to the conditions as detailed in the operations sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields. However, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high impedance circuit.

**Recommended Operating Conditions**  
 (Referenced to V<sub>SS</sub>)

Parameter	Symbol	Value			Unit	Operating Temperature
		Min	Typ	Max		
Supply Voltage	V <sub>CC</sub>	4.5	5.0	5.5	V	0°C to +70°C (ambient)
	V <sub>SS</sub>	0	0	0		
Input High Voltage All Inputs	V <sub>IH</sub>	2.4	—	6.5	V	
Input Low Voltage All Inputs	V <sub>IL</sub>	-1.0	—	0.8	V	

R3

**Capacitance**  
 ( $T_A = 25^\circ\text{C}$ )

Parameter	Symbol	Value			Unit
		Min	Typ	Max	
Input Capacitance $A_0$ to $A_8$ , $D$	$C_{IN1}$	—	—	7	pF
Input Capacitance $\overline{\text{RAS}}$ , $\overline{\text{CAS}}$ and $\overline{\text{W}}$	$C_{IN2}$	—	—	10	pF
Output Capacitance $Q$	$C_{OUT}$	—	—	7	pF

**DC Characteristics**  
 (Recommended operating conditions unless otherwise noted.)

Parameter	Symbol	MB81256-10 MB81256-12 MB81256-15						Unit
		Min	Max	Min	Max	Min	Max	
<b>OPERATING CURRENT*</b> Average Power Supply Current ( $\overline{\text{RAS}}$ , $\overline{\text{CAS}}$ cycling; $t_{RC} = \text{Min.}$ )	$I_{CC1}$	—	70	—	65	—	57	mA
<b>STANDBY CURRENT</b> Power Supply Current ( $\overline{\text{RAS}}/\overline{\text{CAS}} = V_{IH}$ )	$I_{CC2}$	—	4.5	—	4.5	—	4.5	mA
<b>REFRESH CURRENT 1*</b> Average Power Supply Current ( $\overline{\text{RAS}}$ cycling, $\overline{\text{CAS}} = V_{IH}$ ; $t_{RC} = \text{Min.}$ )	$I_{CC3}$	—	60	—	55	—	50	mA
<b>PAGE MODE CURRENT*</b> Average Power Supply Current ( $\overline{\text{RAS}} = V_{IL}$ , $\overline{\text{CAS}}$ cycling; $t_{PC} = \text{Min.}$ )	$I_{CC4}$	—	35	—	30	—	25	mA
<b>REFRESH CURRENT 2*</b> Average Power Supply Current ( $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ ; $t_{RC} = \text{Min.}$ )	$I_{CC5}$	—	65	—	60	—	55	mA
<b>INPUT LEAKAGE CURRENT</b> Any Input, ( $V_{IN} = 0\text{V}$ to $5.5\text{V}$ , $V_{CC} = 5.5\text{V}$ , $V_{SS} = 0\text{V}$ , all other pins not under test = $0\text{V}$ )	$I_{IL}$	-10	10	-10	10	-10	10	$\mu\text{A}$
<b>OUTPUT LEAKAGE CURRENT</b> (Data is disabled, $V_{OUT} = 0\text{V}$ to $5.5\text{V}$ )	$I_{OL}$	-10	10	-10	10	-10	10	$\mu\text{A}$
<b>OUTPUT LEVEL</b> Output Low Voltage ( $I_{OL} = 4.2\text{mA}$ )	$V_{OL}$	—	0.4	—	0.4	—	0.4	V
<b>OUTPUT LEVEL</b> Output High Voltage ( $I_{OH} = -5.0\text{mA}$ )	$V_{OH}$	2.4	—	2.4	—	2.4	—	V

Note\*:  $I_{CC}$  is dependent on output loading and cycle rates. Specified values are obtained with the output open.

**AC Characteristics**  
(Recommended operating conditions unless otherwise noted.)

*R09*

Parameter	Notes	Symbol		MBS1256-10		MBS1256-12		MBS1256-15		Unit
		Alternate	*Standard	Min	Max	Min	Max	Min	Max	
Time between Refresh		$t_{REF}$	TRVRV	—	4	—	4	—	4	ms
Random Read/Write Cycle Time		$t_{RC}$	TRELREL	210	—	230	—	260	—	ns
Read-Write Cycle Time		$t_{RWC}$	TRELREL	210	—	230	—	260	—	ns
Access Time from $\overline{RAS}$	(4), (6)	$t_{RAC}$	TRELQV	—	100	—	120	—	150	ns
Access Time from $\overline{CAS}$	(5), (6)	$t_{CAC}$	TCELQV	—	50	—	60	—	75	ns
Output Buffer Turn off Delay		$t_{OFF}$	TCEHQZ	0	25	0	25	0	30	ns
Transition Time		$t_T$	TT	3	50	3	50	3	50	ns
$\overline{RAS}$ Precharge Time		$t_{RP}$	TREHREL	90	—	100	—	100	—	ns
$\overline{RAS}$ Pulse Width		$t_{RAS}$	TRELREH	110	100000	120	100000	150	100000	ns
$\overline{RAS}$ Hold Time		$t_{RSH}$	TCELREH	60	—	60	—	75	—	ns
$\overline{CAS}$ Pulse Width		$t_{CAS}$	TCELCEH	60	100000	60	100000	75	100000	ns
$\overline{CAS}$ Hold Time		$t_{CSH}$	TRELCEH	110	—	120	—	150	—	ns
$\overline{RAS}$ to $\overline{CAS}$ Delay Time	(4), (7)	$t_{RCD}$	TRELCEL	20	50	22	60	25	75	ns
$\overline{CAS}$ to $\overline{RAS}$ Set Up Time		$t_{CRS}$	TCEXREL	15	—	20	—	20	—	ns
Row Address Set Up Time		$t_{ASR}$	TAVREL	0	—	0	—	0	—	ns
Row Address Hold Time		$t_{RAH}$	TRELAX	10	—	12	—	15	—	ns
Column Address Set Up Time		$t_{ASC}$	TAVCEL	0	—	0	—	0	—	ns
Column Address Hold Time		$t_{CAH}$	TCELAX	15	—	20	—	25	—	ns
Read Command Set Up Time		$t_{RCS}$	TWHCEL	0	—	0	—	0	—	ns
Read Command Hold Time Referenced to $\overline{CAS}$	(10)	$t_{RCH}$	TCEHWX	0	—	0	—	0	—	ns
Read Command Hold Time Referenced to $\overline{RAS}$	(10)	$t_{RRH}$	TREHWX	20	—	20	—	20	—	ns
Write Command Set Up Time	(8)	$t_{WCS}$	TWLCEL	0	—	0	—	0	—	ns
Write Command Pulse Width		$t_{WP}$	TWLWH	15	—	20	—	25	—	ns
Write Command Hold Time		$t_{WCH}$	TCELWH	15	—	20	—	25	—	ns
Write Command to $\overline{RAS}$ Lead Time		$t_{RWL}$	TWLREH	40	—	50	—	60	—	ns
Write Command to $\overline{CAS}$ Lead Time		$t_{CWL}$	TWLCEH	40	—	50	—	60	—	ns
Data In Set Up Time		$t_{DS}$	TDVCEL	0	—	0	—	0	—	ns
Data In Hold Time		$t_{DH}$	TCELDX	15	—	20	—	25	—	ns
$\overline{CAS}$ to $\overline{W}$ Delay	(8)	$t_{CWD}$	TCELWL	15	—	20	—	25	—	ns
Refresh Set Up Time for $\overline{CAS}$ Referenced to $\overline{RAS}$		$t_{FCS}$	TCELREL	20	—	25	—	30	—	ns
Refresh Hold Time for $\overline{CAS}$ Referenced to $\overline{RAS}$		$t_{FCH}$	TRELCEX	20	—	25	—	30	—	ns
Page Mode Read/Write Cycle Time		$t_{PC}$	TCELCEL	100	—	120	—	150	—	ns
Page Mode Read-Write Cycle Time		$t_{PRWC}$	TCEHCEH	100	—	120	—	150	—	ns
Page Mode $\overline{CAS}$ Precharge Time		$t_{CP}$	TCEHCEL	40	—	50	—	65	—	ns
Refresh Counter Test $\overline{RAS}$ Pulse Width	(9)	$t_{TRAS}$	TRELREH	230	10000	265	10000	320	10000	ns
Refresh Counter Test Cycle Time	(9)	$t_{RTC}$	TRELREL	330	—	375	—	430	—	ns
$\overline{RAS}$ Precharge to $\overline{CAS}$ Active Time		$t_{RPC}$	TREHCEL	20	—	20	—	20	—	ns
Refresh Counter Test $\overline{CAS}$ Precharge Time	(9)	$t_{CPT}$	TCEHCEL	50	—	60	—	70	—	ns
$\overline{CAS}$ Precharge Time for $\overline{CAS}$ before $\overline{RAS}$ Refresh Cycle		$t_{CPR}$	TCEHCEL	20	—	25	—	30	—	ns

See Notes on following page.

Notes: \*These symbols are described in IEEE STD. 662-1980: IEEE Standard terminology for semiconductor memory.

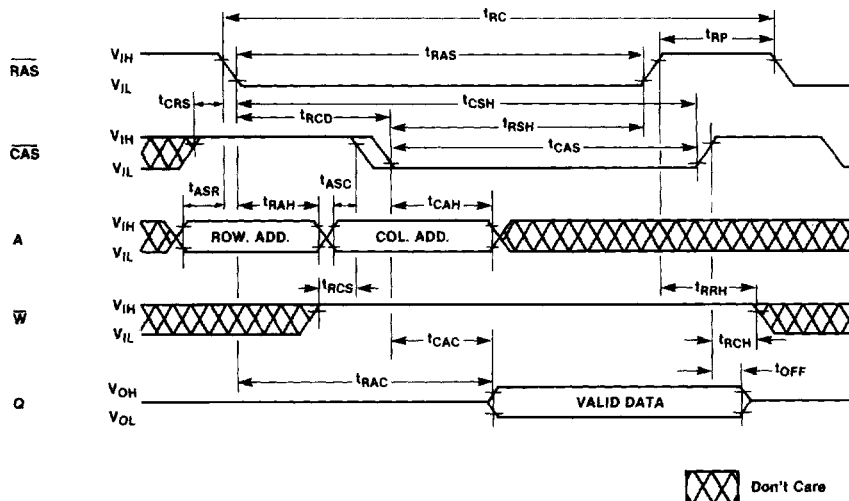
**AC Characteristics,**  
 continued

**Notes:**

1. An initial pause of 200 $\mu$ s is required after power up, followed by any 8  $\overline{\text{RAS}}$  cycles, before proper device operation is achieved.  
If the internal refresh counter is to be effective, a minimum of 8  $\overline{\text{CAS}}$  before  $\overline{\text{RAS}}$  refresh initialization cycles are required.
2. AC characteristics assume  $t_T = 5\text{ns}$ .
3.  $V_{IH}$  (Min.) and  $V_{IL}$  (Max.) are reference levels for measuring timing of input signals. Also, transition times are measured between  $V_{IH}$  and  $V_{IL}$ .
4.  $t_{\text{RCD}}$  is specified as a reference point only. If  $t_{\text{RCD}} \leq t_{\text{RCD}}(\text{Max.})$  the specified maximum value of  $t_{\text{RAC}}(\text{Max.})$  can be met. If  $t_{\text{RCD}} > t_{\text{RCD}}(\text{Max.})$  then  $t_{\text{RAC}}$  is increased by the amount that  $t_{\text{RCD}}$  exceeds  $t_{\text{RCD}}(\text{Max.})$ .
5. Assumes that  $t_{\text{RCD}} > t_{\text{RCD}}(\text{Max.})$ .
6. Measured with a load equivalent to 2 TTL loads and 100pF.
7.  $t_{\text{RCD}}(\text{Min.}) = t_{\text{RAH}}(\text{Min.}) + 2t_T + t_{\text{ASC}}(\text{Min.})$ .
8.  $t_{\text{WCS}}$  and  $t_{\text{CWD}}$  are non restrictive operating parameters, and are included in the data sheet as electrical characteristics only. If  $t_{\text{WCS}} > t_{\text{WCS}}(\text{Min.})$ , the cycle is an early write cycle, and the data out pin will remain open circuit (High Impedance) throughout the entire cycle.  
If  $t_{\text{CWD}} > t_{\text{CWD}}(\text{Min.})$ , the cycle is a read-write cycle and data out will contain data read from the selected cell. If neither of the above sets of conditions is satisfied, the condition of the data out is indeterminate.
9. Test mode write cycle only.
10. Either  $t_{\text{RCH}}$  or  $t_{\text{RRH}}$  must be satisfied for a read cycle.

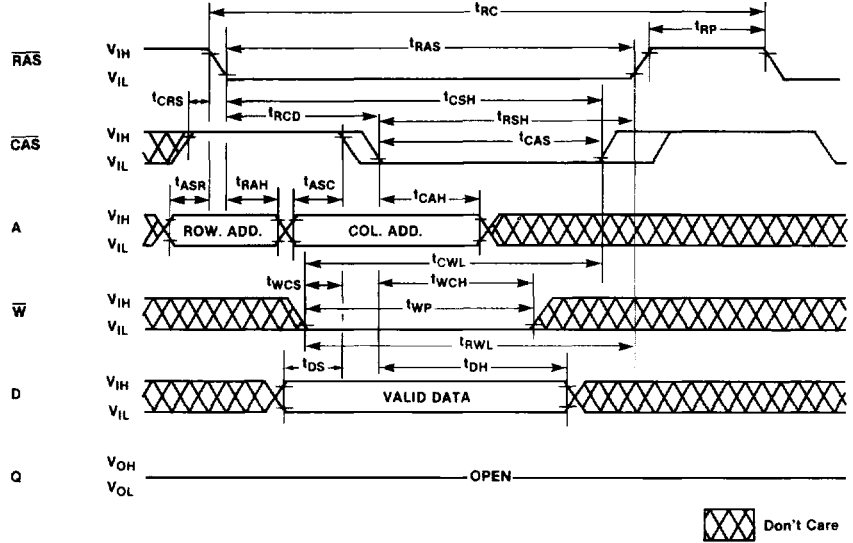
**Timing Diagrams**

**Read Cycle**

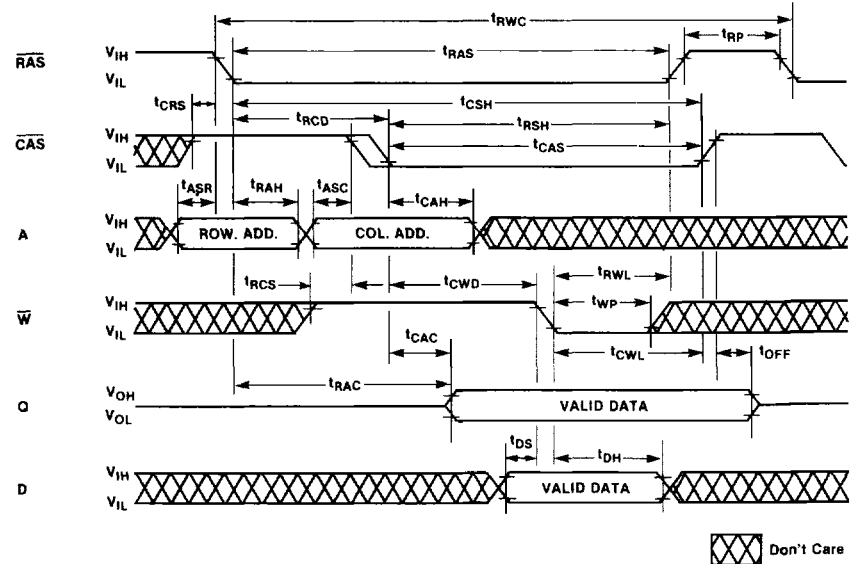


Timing Diagrams, continued

Write Cycle (Early Write)



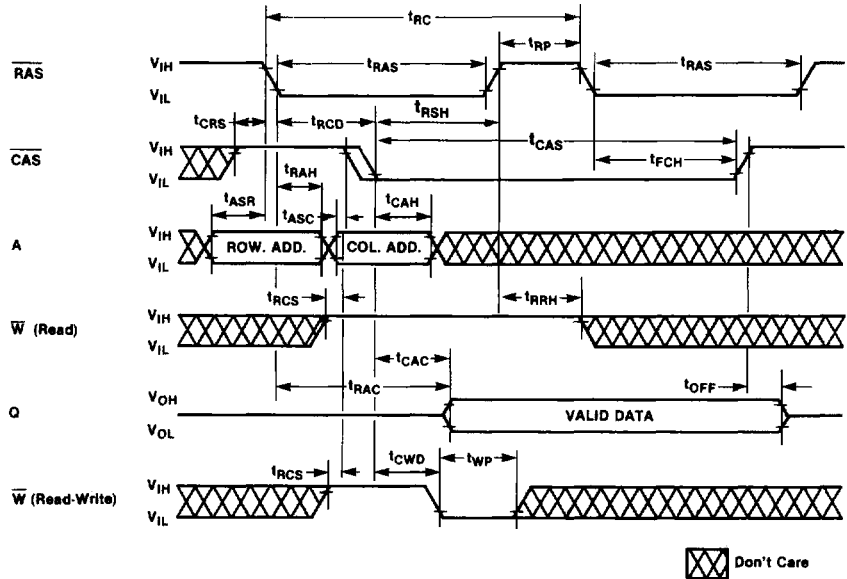
Read-Write/Read-Modify-Write Cycle





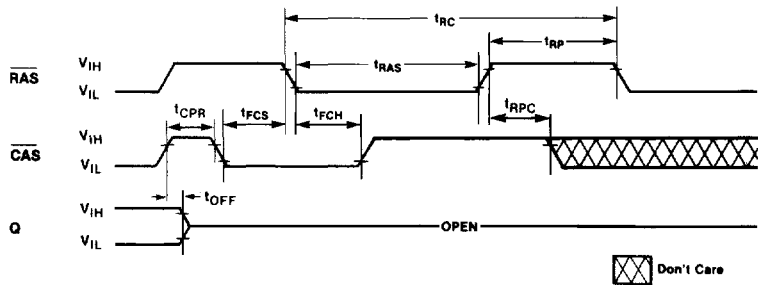
Timing Diagrams, continued

Hidden Refresh Cycle



"CAS-Before-RAS" Refresh Cycle

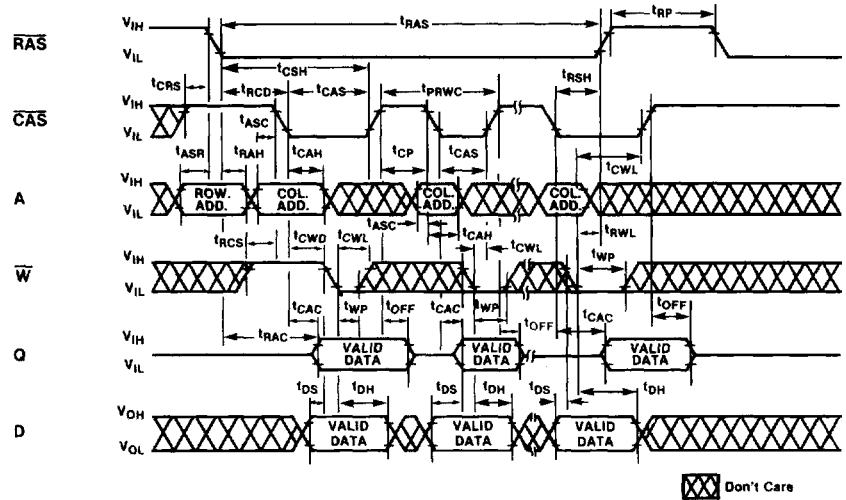
NOTE: A,  $\bar{W}$ , D = Don't Care



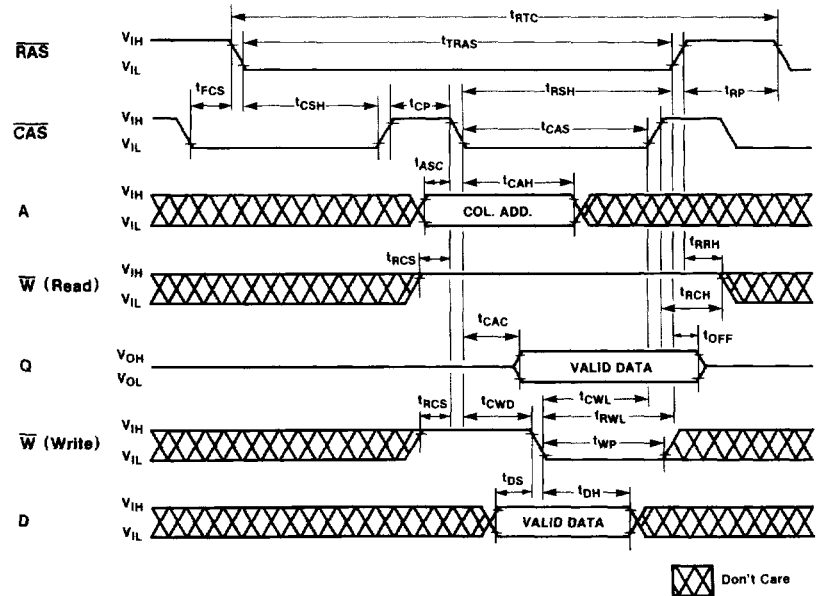


Timing Diagrams, continued

Page Mode Read-Write Cycle



"CAS-Before-RAS" Refresh Counter Test Cycle



## Description

### Simplified Timing Requirement

The MB81256 has improved circuitry that eases timing requirements for high speed access operations. The MB81256 can operate under the condition of  $t_{RCD}(\max) = t_{CAC}$ , thus providing optimal timing for address multiplexing. In addition, the MB81256 has minimal hold times for Addresses ( $t_{CAH}$ ), Write-Enable ( $t_{WCH}$ ) and Data-in ( $t_{DHI}$ ). The MB81256 provides higher throughput in inter-leaved memory system applications. Fujitsu has made the timing requirements that are referenced to RAS non-restrictive and deleted them from the data sheet. These include  $t_{AR}$ ,  $t_{WCR}$ ,  $t_{DHR}$  and  $t_{RWD}$ . As a result, the hold times of the Column Address, D and  $\bar{W}$  as well as  $t_{CWD}$  ( $\bar{CAS}$  to  $\bar{W}$  Delay) are not restricted by  $t_{RCD}$ .

### Fast Read-Write Cycle

The MB81256 has a fast read-modify-write cycle which is achieved by precise control of the three-state output buffer as well as by the simplified timings described in the previous section. The output buffer is controlled by the state of  $\bar{W}$  when  $\bar{CAS}$  goes "low". When  $\bar{W}$  is "low" during a  $\bar{CAS}$  transition to "low", the MB81256 goes into the early write mode in which the output floats and the common I/O bus can be used on the system level. When  $\bar{W}$  goes "low", after  $t_{CWD}$  following a  $\bar{CAS}$  transition to "low", the MB81256 goes into the delayed write mode. The output then contains the data from the cell selected and the data from D is written into the cell selected. Therefore, a very fast read-write cycle ( $t_{RWC} = t_{RC}$ ) is possible with the MB81256.

### Address Inputs

A total of eighteen binary input address bits are required to decode any 1 of 262,144 cell locations within the MB81256. Nine row-address bits are established on the input pins ( $A_0$  through  $A_8$ ) and are latched with the Row Address Strobe (RAS). Nine column address bits are established on the input pins and latched with the

Column Address Strobe ( $\bar{CAS}$ ). All row addresses must be stable on or before the falling edge of RAS.  $\bar{CAS}$  is internally inhibited (or "gated") by RAS to permit triggering of  $\bar{CAS}$  as soon as the Row Address Hold/Time ( $t_{RAH}$ ) specification has been satisfied and the address inputs have been changed from row addresses to column addresses.

### Write Enable

The read or write mode is selected with the  $\bar{W}$  input. A logic "high" on  $\bar{W}$  dictates read mode. A logic "low" dictates write mode. The data input is disabled when the read mode is selected.

### Data Input

Data is written into the MB81256 during a write or read-write cycle. The last falling edge of  $\bar{W}$  or  $\bar{CAS}$  is a strobe for the data-in (D) register. In a write cycle, if  $\bar{W}$  is brought "low" (write mode) before  $\bar{CAS}$ , D is strobed by  $\bar{CAS}$ , and the set-up and hold times are referenced to  $\bar{CAS}$ . In a read-write cycle,  $\bar{W}$  will be delayed until  $\bar{CAS}$  has made its negative transition. Thus D is strobed by  $\bar{W}$ , and set-up and hold times are referenced to  $\bar{W}$ .

### Data Output

The output buffer is three-state TTL compatible with a fan-out of two standard TTL loads. Data out is the same polarity as data in. The output is in a high impedance state until  $\bar{CAS}$  is brought "low". In a read cycle, or a read-write cycle, the output is valid after  $t_{RAC}$  from transition of RAS when  $t_{RCD}(\max)$  is satisfied, or after  $t_{CAC}$  from transition of  $\bar{CAS}$  when the transition occurs after  $t_{RCD}(\max)$ . Data remains valid until  $\bar{CAS}$  is returned to "high". In a write cycle, the identical sequence occurs, but data is not valid.

### Page Mode

Page mode operation permits strobing the row address into the MB81256 while maintaining RAS at a logic low (0) throughout all successive memory operations in which the row

address doesn't change. Thus, the power dissipated by the negative going edge of RAS is saved. Access and cycle times are decreased because the time normally required to strobe a new row address is eliminated.

### RAS-Only Refresh

Refresh of dynamic memory cells is accomplished by performing a memory cycle at each of the 256 row-addresses ( $A_0 - A_7$ ) at least every 4 ms. RAS-only refresh avoids any output during refresh because the output buffer is in the high impedance state unless  $\bar{CAS}$  is brought "low". Strobing each of the 256 row-addresses ( $A_0 - A_7$ ) with RAS will cause all bits in each row to be refreshed. RAS-only refresh results in a substantial reduction in power dissipation.

### $\bar{CAS}$ -before-RAS Refresh

$\bar{CAS}$ -before-RAS refreshing available on the MB81256 offers an alternate refresh method. If  $\bar{CAS}$  is held "low" for the specified period ( $t_{FCS}$ ) before RAS goes to "low", on-chip refresh control clock generators and the refresh address counter are enabled, and an internal refresh operation takes place. After the refresh operation is performed, the refresh address counter is automatically incremented in preparation for the next  $\bar{CAS}$ -before-RAS refresh operation.

### Hidden Refresh

A hidden refresh cycle may take place while maintaining the latest valid data at the output by extending the  $\bar{CAS}$  active time. For the MB81256, a hidden refresh cycle is a  $\bar{CAS}$ -before-RAS refresh cycle. The internal refresh address counter provides the refresh addresses as in a normal  $\bar{CAS}$ -before-RAS refresh cycle.

### $\bar{CAS}$ -before-RAS Refresh Counter Test Cycle

A special timing sequence using the  $\bar{CAS}$ -before-RAS counter test cycle provides a convenient method of verifying the functionality of the  $\bar{CAS}$ -before-RAS refresh activated circuitry.

After the  $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$  refresh operation, if  $\overline{\text{CAS}}$  goes to "high" and then goes to "low" again while  $\overline{\text{RAS}}$  is held "low", the read and write operation are enabled.

This is shown in the  $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$  counter test cycle timing diagram. A memory cell can be addressed with 9 row address bits and 9 column address bits defined as follows:

**A ROW ADDRESS**

Bits  $A_0$  through  $A_7$  are defined by the refresh counter. The other bit  $A_8$  is set "high" internally.

**A COLUMN ADDRESS**

All the bits  $A_0$  through  $A_8$  are defined by latching levels on  $A_0$  through  $A_8$  at the second falling edge of  $\overline{\text{CAS}}$ .

**Suggested  $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$  Counter Test Procedure**

The timing, as shown in the  $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$  Counter Test Cycle, is used for all the following operations:

- (1). Initialize the internal refresh counter. For this operation, 8 cycles are required.
- (2). Write a test pattern of "low"s into memory cells at a single column address and 256 row address.
- (3). Using a read-modify-write cycle, read the "low" written at the last operation (Step 2) and write a new "high" in the same cycle. This cycle is repeated 256 times, and "high"s are written into the 256 memory cells.
- (4). Read the "high"s written at the last operation (Step 3).

- (5). Complement the test pattern and repeat steps (2), (3) and (4).